D2661, APRIL 1982-REVISED MARCH 1988

- Fully Buffered to Offer Maximum Isolation from External Disturbance
- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

These devices contain two independent J-K negative-edge-triggered flip-flops. A low level at the preset and clear inputs sets or resets the outputs regardless of the levels of the other inputs. When preset and clear are inactive (high), data at the J and K inputs meeting the setup time requirements are transferred to the outputs on the negative-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold time interval, data at the J and K inputs may be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by tying J and K high.

The SN54LS112A and SN54S112 are characterized for operation over the full military temperature range of ~55 °C to 125 °C. The SN74LS112A and SN74S112A are characterized for operation from 0 °C to 70 °C.

FUNCTION TABLE (each flip-flop)

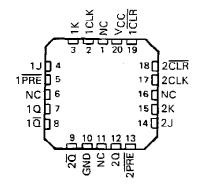
	IN		OUTPUTS			
PRE	CLR	CLK	J	K	a	₫
L	Н	Х	X	Х	Н	L
н	L	×	Х	X	L	Н
L	L	×	х	Х	Н [†]	H [†]
н	Н	1	L	L	ΩO	ᾱo
H	Н	1	Н	L	Н	L
Н	H	1	L	н	L	н
Н	Н	1	Н	н	TOG	GLE
H	_ H	Н	X	х	αo	₫o

[†] The output levels in this configuration are not guaranteed to meet the minimum levels for VOH if the lows at preset and clear are near VIL minimum. Furthermore, this configuration is nonstable; that is, it will not persist when either preset or clear returns to its inactive (high) level.

SN54LS112A, SN54S112 . . . J OR W PACKAGE SN74LS112A, SN74S112A . . . D OR N PACKAGE (TOP VIEW)

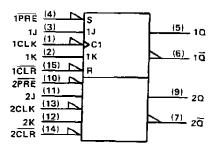
_	_		
1CLK[]1	\cup_{16}	□vcc
1K []2	15	1 CLR
1J[]3	14	2CLR
1PRE]4	13	2CLK
10[]5	12	<u></u> 2κ
10[]6	11	2J
20 [7	10	2PRE
GND [8	9	20

SN54LS112A, SN54S112...FK PACKAGE (TOP VIEW)



NC-No internal connection

logic symbol‡

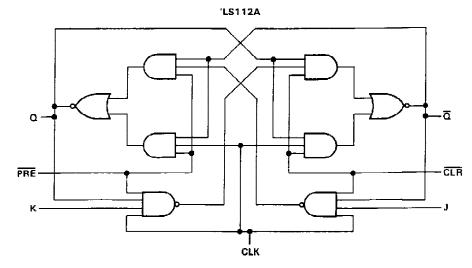


[‡]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

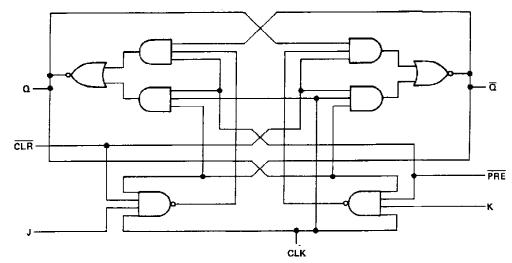
Pin numbers shown are for D, J, N, and W packages.

SN54LS112A, SN54S112, SN74LS112A, SN74S112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

logic diagrams (positive logic)

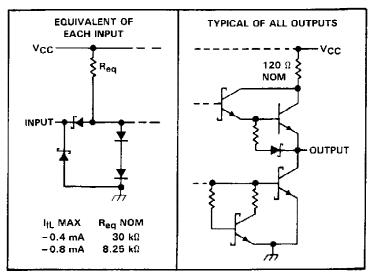


SN54S112, SN74LS112A

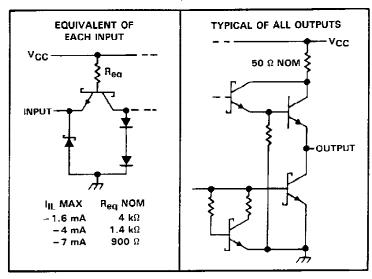


schematics of inputs and outputs

'LS112A



SN54S112, SN74S112A



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	
Input voltage: 'LS112A	<i></i>
SN54LS112, SN74LS	112A
Operating free-air temperature range:	\$N54'55°C to 125°C
	\$N74'
Storage temperature range	

NOTE 1: Voltage values are with respect to network ground terminal.

SN54LS112A, SN74LS112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

recommended operating conditions

			SN	154LS11	2A	SN	74LS11	2A	LIBUT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	٧
ViH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			8.0	٧
Юн	High-level output current				-0.4		·	-0.4	mА
OL	Low-level output current				4			8	mA
fclock	Clock frequency		0		30	0		30	MHz
	Pulse duration	CLK high	20			20			D.C.
t _W	roise duration	PRE or CLR low	25	-		25			ns
		Data high or low	20			20		_ "	
t _{su}	Set up time-before CLK1	CLR inactive	25			25			ns
		PRE inactive	20			20			
th	Hold time-data after CLK1		0			0			пş
Тд	Operating free-air temperature		- 55		125	0		70	°С

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DAMETER	TEST	CONDITIONS†		SI	154LS11	2A	SN74LS112A			
Ρ,	ARAMETER	IEST	CONDITIONS		MIN	TYP!	MAX	MIN	TYP‡	MAX	UNIT
v_{iK}		V _{CC} = MIN,	I _I = -18 mA				-1.5			1.5	V
Vон		V _{CC} = MIN, I _{OH} = -0.4 mA	$V_{IH} = 2 V$,	V _{IL} ≠ MAX,	2.5	3.4		2.7	3.4		V
1.0	•	V _{CC} = MIN, I _{OL} = 4 mA	V _{IL} = MAX,	V _{IH} = 2 V,		0.25	0.4		0.25	0.4	V
VOL		V _{CC} = MIN, I _{OL} = 8 mA	$V_{IL} = MAX$, $V_{IH} = 2 V$,						0.35	0.5	
	J or K						0.1			0.1	
Ιį	CLR or PRE	V _{CC} = MAX,	V _I = 7 V				0.3			0.3	mA
	CLK	1			-		0.4			0.4	
	J or K		·				20			20	
ΉΗ	CLR or PRE	V _{CC} = MAX,	$V_{\parallel} = 2.7 \text{ V}$		-		60	_		60	μА
	CLK	1					80			80	
1	J or K	V _{CC} = MAX,	V. = 0.4 V				-0.4			-0.4	mA
IIL .	All other	ACC - MINY	VI = 0.4 V				-0.8			-0.8	IIIA
los [§]		VCC = MAX,	see Note 2		- 20		- 100	- 20		- 100	mA
ICC (T	otal)	V _{CC} = MAX,	see Note 3			4	6		4	6	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 $^{^{\}ddagger}$ All typical values are at $V_{CC} = 5 \text{ V}$, $T_{A} = 25 \,^{\circ}\text{C}$.

Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

NOTES: 2. For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with $V_0 = 2.25 \text{ V}$ and 2.125 V for the '54 family and the '74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.

^{3.} With all outputs open, ICC is measured with the Q and \overline{Q} outputs high in turn. At the time of measurement, the clock input is grounded.

switching characteristics, V_{CC} = 5 V, T_A = 25 °C (see Note 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	Mi	N TYP	MAX	UNIT
f _{max}			•	3	0 45		MHz
tPLH	CLR. PRE or CLK	Q or $\overline{\mathbf{Q}}$	$R_L = 2 k\Omega$, $C_L = 15 \mu$	oF	15	20	กร
†PHL	CLM, PRE OF CLK	2014		[15	20	пѕ

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

SN54S112, SN74S112A DUAL J-K NEGATIVE EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

recommended operating conditions

			SN54S112		SN74S112A			UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX	DINIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
ViH	High-level input voltage	-	2			2			V
VIL	Low-level input voltage				0.8			0.8	٧
ЮН	High-level output current				- 1			- 1	mA
loL	Low-level output current				20			20	mΑ
		CLK high	6			6		.,,	
tw	Pulse duration	CLK low	6.5		- -	6.5			пѕ
		PRE or CLR low	8			8			
t _{SU}	Set up time-before CLK1	Data high or low	7			7			ns
th	Hold time-data after CLK↓		0			0			ns
TA	Operating free-air temperature		-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			CONDITIONS		S	N54S1	2	SN74S112A			
PARAMETER		IESI	CONDITIONS		MIN	TYP [‡]	MAX	MIN	TYP‡	MAX	UNIT
VIK		V _{CC} = MIN.	II = -18 mA	****		-	-1.2			-1.2	٧
VoH		V _{CC} = MIN, I _{OH} = -1 mA	V _{IH} = 2 V,	VIL = MAX,	2.5	3.4		2.7	3.4		٧
VOL		V _{CC} = MIN, I _{OL} = 20 mA	V _{IH} = 2 V,	V _{IL} = 0.8 V,			0.5			0.5	٧
I _I			V ₁ = 5.5 V				1			1	mA
	J or K	VCC = MAX.	V - 2.7 M				50			50	μΑ
ŀН	All other	T VCC = MAX.	V = 2.7 V				100			100	μΑ
	J or K						- 1.6			-1.6	
	CLR [§]],,	V 05V				-7			-7	mΑ
ΙΙΓ	PRE 5	V _{CC} = MAX,	VI = 0.5 V			•	-7			-7	mA
	CLK	1					-4			-4	
los¶		V _{CC} = MAX			-40	•	- 100	- 40		~ 100	mA
CC#		V _{CC} = MAX,	see Note 3			15	25		15	25	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C.

[§]Clear is tested with preset high and preset is tested with clear high.

Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

[#]Values are average per flip-flop.

NOTE 3: With all outputs open, I_{CC} is measured with the Q and \overline{Q} outputs high in turn. At the time of measurement, the clock input is grounded.

switching characteristics, VCC = 5 V, TA = 25 °C (see Note 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
fmax				80	125		MHz
tPLH	PRE or CLR	Q or Q			4	7	ns
4	PRE or CLR (CLK high)	Q or Q	B. 200.0 0. 45.5		5	7	
†PHL	PRE or CLR (CLK low)		$R_L = 280 \Omega$, $C_L = 15 pF$		5	7	ns
^t PLH	CLK	Q or $\overline{\mathbf{Q}}$	7		4	7	ns
tPHL .	CLK		<u> </u>		5	7	ns

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

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PACKAGE OPTION ADDENDUM





PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
JM38510/07102BEA	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
JM38510/07102BFA	ACTIVE	CFP	W	16	1	None	Call TI	Level-NC-NC-NC
JM38510/30103B2A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
JM38510/30103BEA	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
JM38510/30103BFA	ACTIVE	CFP	W	16	1	None	Call TI	Level-NC-NC-NC
SN54LS112AJ	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
SN54S112J	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
SN74LS112AD	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LS112ADR	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LS112AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS112AN3	OBSOLETE	PDIP	N	16		None	Call TI	Call TI
SN74LS112ANSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74S112AD	OBSOLETE	SOIC	D	16		None	Call TI	Call TI
SN74S112ADR	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74S112AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S112AN3	OBSOLETE	PDIP	N	16		None	Call TI	Call TI
SN74S112ANSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SNJ54LS112AFK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54LS112AJ	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
SNJ54LS112AW	ACTIVE	CFP	W	16	1	None	Call TI	Level-NC-NC-NC
SNJ54S112FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54S112J	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
SNJ54S112W	ACTIVE	CFP	W	16	1	None	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

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⁽²⁾ Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder



PACKAGE OPTION ADDENDUM

28-Feb-2005

temperature.

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